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					Attorney Docket No.		98-P-009C2 (850063.529C1
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CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail in an envelope addressed to: Commissioner for Patents, Washington, D.C. 20231 on the date specified below.

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PATENT 8/13/03

HE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants

Shin Hwa Li et al.

Application No.

09/632,388

Filed

August 3, 2000

For

SEMICONDUCTOR STRUCTURE HAVING AN IMPROVED

PRE-METAL DIELECTRIC STACK AND METHOD FOR

FORMING THE SAME

Examiner

Julio J. Maldonado

Art Unit

2823

Docket No.

98-P-009C2 (850063.529C1)

Date

August 6, 2002

Box Non-Fee Amendment Commissioner for Patents Washington, DC 20231

AMENDMENT

Commissioner for Patents:

In response to the office action dated May 6, 2002 (the "Office Action"), please amend the application as follows:

In the Specification:

Please replace the paragraph beginning at page 4, line 10, with the following rewritten paragraph:

FI

Referring to Figure 4, a layer 38 is formed over the BPSG layer 6 before CMP. In one embodiment, the layer 38 is conventionally formed from plasma-enhanced tetraethyl orthosilicate (PE-TEOS). The layer 38 acts as a sacrificial layer for the CMP process. In one embodiment, the thickness of the layer 38 is between approximately 8,000 - 20,000 angstrom, for example about 12,000 angstroms. The thickness of the BPSG layer 6 is between approximately 1,500 - 8,000 angstroms, for example 6,000 angstroms. The thickness of the